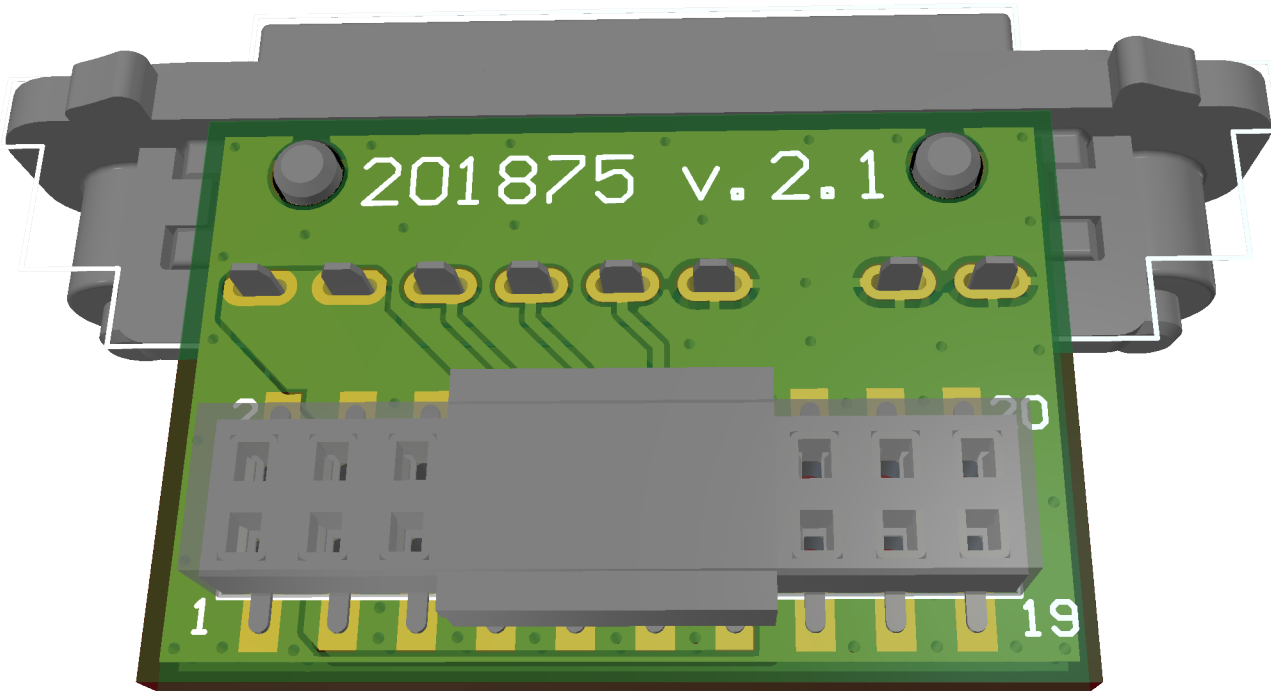
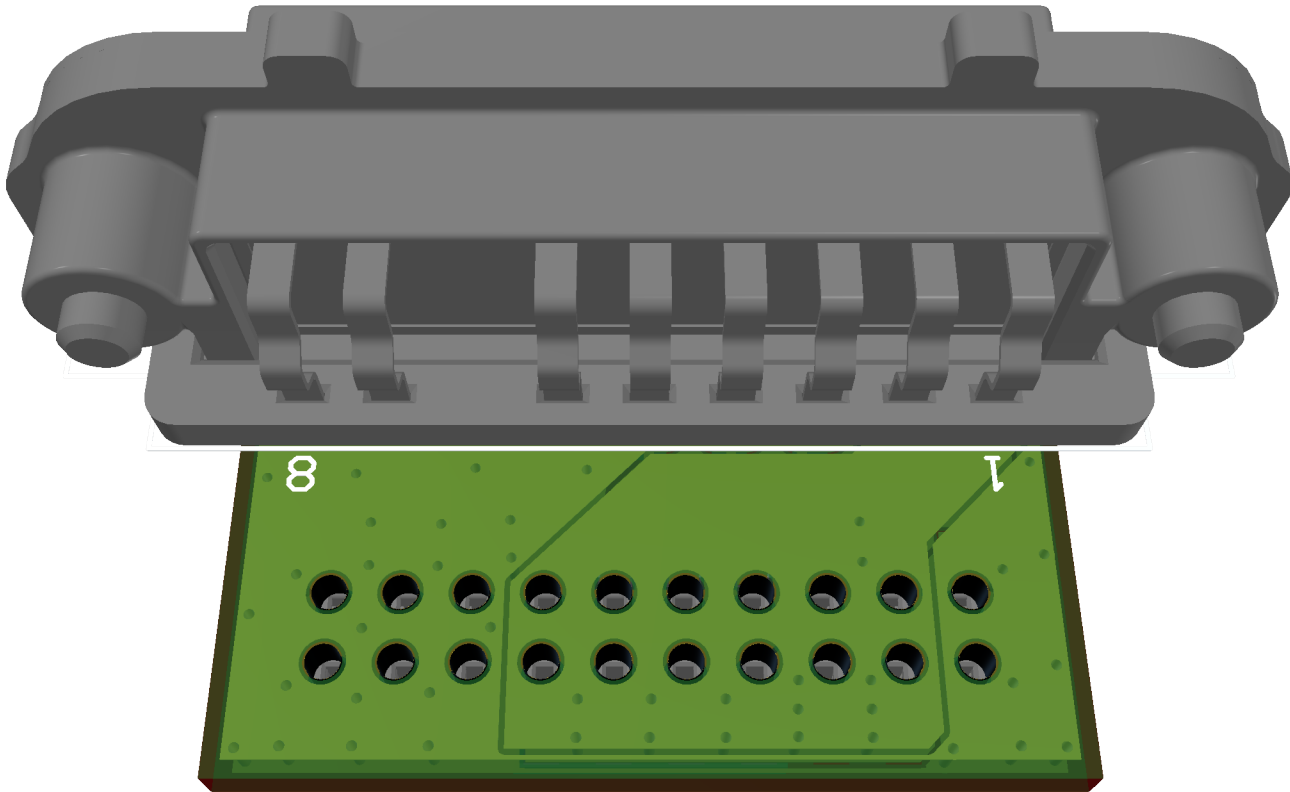


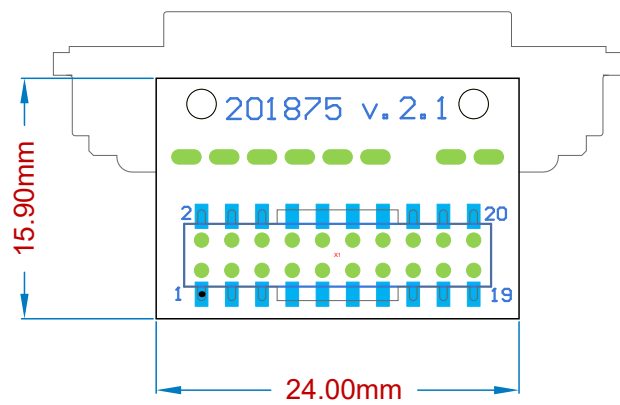
View from Top side



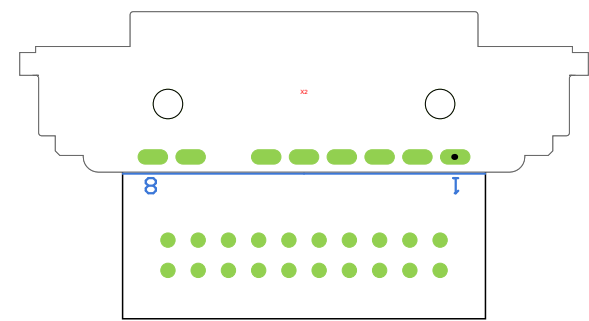
View from Bottom side

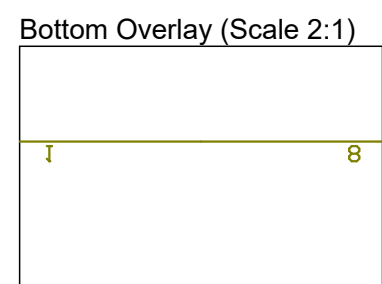
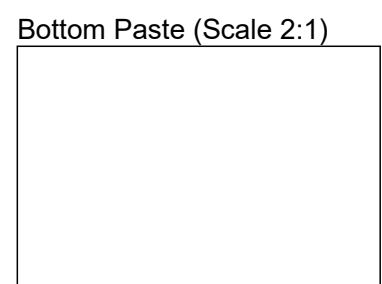
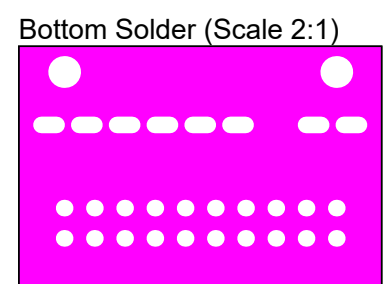
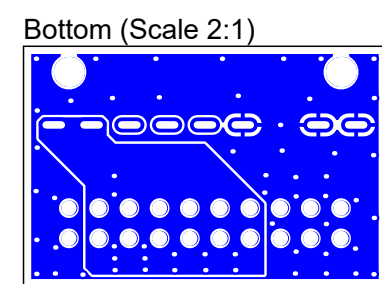
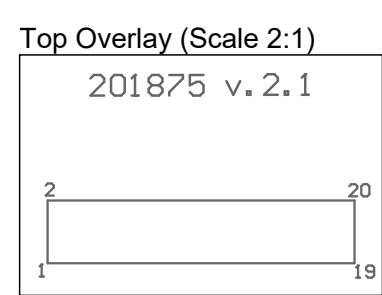
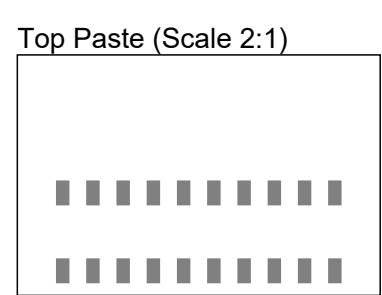
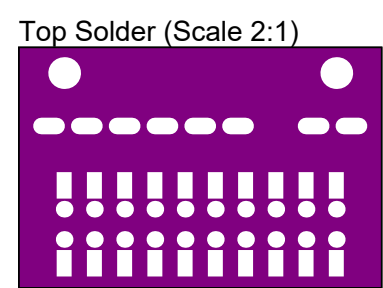
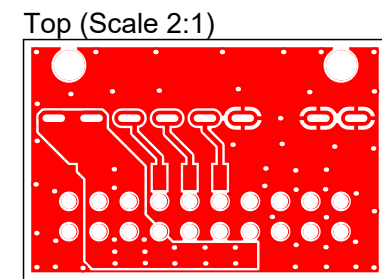


View from Top side (Scale 2:1)



View from Bottom side (Scale 2:1)





Layer Stack

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.025mm	SM-001	Solder Mask	GTS
CF-004	Top	0.035mm		Signal	GTL
		1.430mm	FR-4	Dielectric	
CF-004	Bottom	0.035mm		Signal	GBL
Surface Material	Bottom Solder	0.025mm	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.551mm					

PCB Specification

IPC class	2
Material	FR4 (Tg 150)
Surface finish	chemical gold (ENIG)
Minimum track space	150 µm
Minimum drills	0.2 mm
Solder stop	both sides black
Marking print	both sides white
Lead free marking	yes
Production date marking	yes
Mechanical treatment (panel only)	scored
Via type	tented
Qualification and performance specification	IPC-6012
Material compliance	All materials must be RoHS compliant
Total board thickness	1.55 mm ± 10 %
Laminate material specification	IPC-4101
Finished hole sizes specification	IPC-2222
Impedance control	None
Electrical testing specification	IPC-9252
Cleanliness requirements	IPC-5704

Stencil Specification

Thickness	120 µm
Pad size reduction	10 %

Assembly Specification

IPC class	2
Requirements for soldering and assembly	IPC J-STD-001
Requirements for inspection	IPC-A-610
Material compliance	All materials must be RoHS compliant

Assembled PCB SAP numbers

Variant	SAP number
2.1.A	201869

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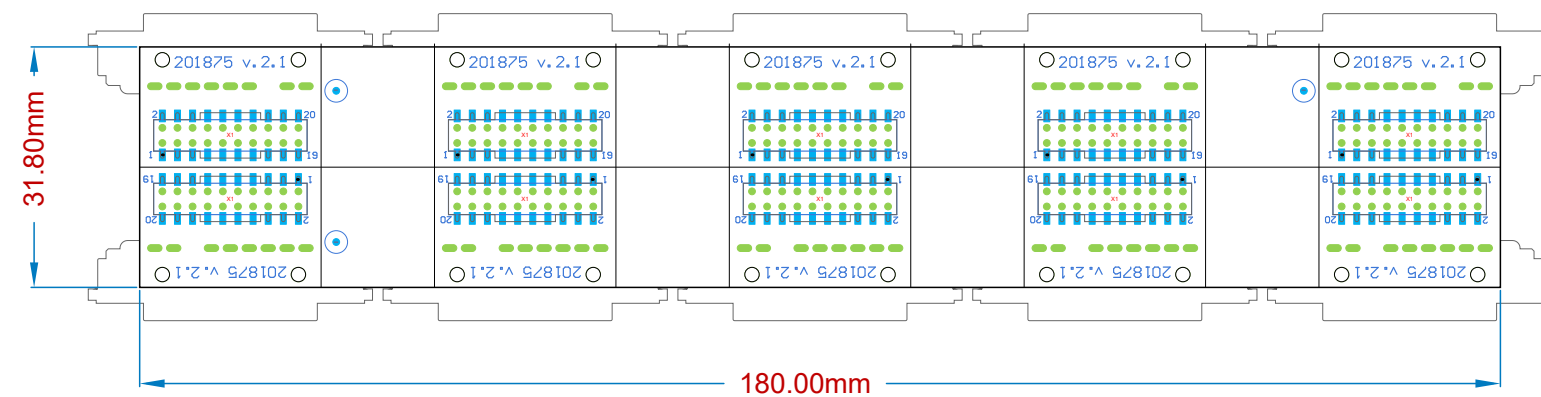
3

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4

View from Top side (Scale 1:1)



View from Bottom side (Scale 1:1)

